IEC 61191-1,-2,-3,-4 Soldering assembly requirements maintenance PG

◆ Purpose & Scope

- In response to the revision of the IEC 61191 series (PRINTED BOARD ASSEMBLIES – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies), a review plan was compiled in Japan and proposed to the IEC / TC91WG2 project leader (Germany). We plan revision reflecting opinion.

◆ Activities Overview

- Revisions corresponding to four standard series: IEC 61191-1 (Generic specification), -2 (Surface mount), -3 (Through-hole mount), -4 (Terminal soldered requirements). Discussion and submission of Japanese comments.
- Proposal and discussion of Japanese opinions at IEC / TC91WG2 international meeting.
- Promoted in cooperation with the IEC / TC91 National Committee and the Welding Society.
- And also works as a subcommittee under the JIS drafting committee and prepares and discusses JIS revision drafts.

◆Standards in charge

IEC	JIS	JEITA	Standard document name
IEC 61191-1 pub. in 2018-09	JIS C 61191-1 drafting in 2019	-	PRINTED BOARD ASSEMBLIES – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly
IEC 61191-2 pub. in 2017-05	JIS C 61191-2 drafted in 2018	-	PRINTED BOARD ASSEMBLIES – Part 2: Sectional specification – Requirements for surface mount soldered assemblies
IEC 61191-3 pub. in 2017-05	JIS C 61191-3 drafted in 2018	-	PRINTED BOARD ASSEMBLIES – Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies
IEC 61191-4 pub. in 2017-07	JIS C 61191-4 drafted in 2018	-	PRINTED BOARD ASSEMBLIES – Part 4: Sectional specification – Requirements for terminal soldered assemblies